



Material Content Data Sheet



Sales Product Name		IPD090N03L G		Issued		29. August 2013		
MA#		MA000687270						
Package		PG-TO252-3-311		Weight*		316.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.720	0.23	0.23	2279	2279
leadframe	inorganic material	phosphorus	7723-14-0	0.049	0.02		154	
	non noble metal	iron	7439-89-6	0.162	0.05		514	
wire	non noble metal	copper	7440-50-8	162.275	51.32	51.39	513233	513901
	non noble metal	aluminium	7429-90-5	0.937	0.30	0.30	2965	2965
encapsulation	organic material	carbon black	1333-86-4	0.324	0.10		1026	
	plastics	epoxy resin	-	19.586	6.19		61944	
leadfinish	inorganic material	silicondioxide	60676-86-0	127.573	40.35	46.64	403478	466448
	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11829	11829
plating	non noble metal	nickel	7440-02-0	0.086	0.03		273	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	274
solder	non noble metal	tin	7440-31-5	0.015	0.00		46	
	noble metal	silver	7440-22-4	0.018	0.01		58	
*deviation	non noble metal	lead	7439-92-1	0.696	0.22	0.23	2200	2304
					Sum in total:		100.00	

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com